

**Amendments to the Claims:**

Kindly replace the previous claim set with the claim set which appears below, in which Claims 18 and 20-25 have been cancelled, Claim 26 has been added and Claims 1 and 3 have been amended to read as follows:

1. (Currently Amended) A lead free soldering material consisting essentially of Sn (tin), 10 wt.% or less Ag (silver), 10 wt.% or less Bi (bismuth), 1 to 3 wt.% Sb (antimony), 0.5 to 3 wt.% or less Cu (copper), and 1.0 wt.% or less Ni (nickel),  
~~wherein the Sb:Bi wt.% ratio is from 1:1.5-3.~~

2. (Cancelled)

3. (Currently Amended) A lead free soldering ~~Soldering~~ material ~~according to Claim 1~~ consisting essentially of 2 to ~~5~~ 10 wt.% Ag, ~~1 to 3 wt.%~~ Bi, 1 to 3 wt.% Sb, 0.5 to ~~1.5~~ 3 wt.% Cu and 0.05 to 0.3 wt.% Ni, wherein the Sb:Bi wt.% ratio is from 1:1.5-3.

4-6. (Cancelled)

7. (Previously Presented) Soldering material according to Claim 1 wherein there exists a ratio Sb:Bi of 1:1.5 to 3, based on the weight of Sb and Bi.

8. (Previously Presented) Soldering material according to Claim 7 having a Ni content of 0.05 to 0.2 wt.%.

9. (Previously Presented) Soldering material according to Claim 1 wherein the soldering material is  $\text{SnAg}_{3.3-4.7}\text{Cu}_{0.3-1.7}\text{Bi}_{2}\text{Sb}_{1}\text{Ni}_{0.2}$ .

10-14. (Cancelled)

15. (Previously Presented) Soldering material according to Claim 3 wherein there exists a ratio Sb:Bi of 1:1.5 to 3, based on the weight of Sb and Bi.

16-18. (Cancelled)

19. (Previously Presented) A solder joint formed from the lead free soldering material of Claim 1.

20-25. (Cancelled)

26. (New) A lead free soldering material consisting essentially of 2 to 10 wt.% Ag, 1 to 3 wt.% Bi, 1 to 3 wt.% Sb, 0.5 to 3 wt.% Cu and 0.05 to 0.3 wt.% Ni.